



## Material Content Data Sheet



<b>Sales Product Name</b>		BTM7740G		<b>Issued</b>		30. April 2015		
<b>MA#</b>		MA001363372						
<b>Package</b>		PG-DSO-28-22		<b>Weight*</b>		809.11 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.615	0.69	0.69	6940	6940
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		89	
	non noble metal	zinc	7440-66-6	0.288	0.04		356	
	non noble metal	iron	7439-89-6	5.754	0.71		7112	
wire	non noble metal	copper	7440-50-8	233.637	28.88	29.64	288759	296316
	non noble metal	aluminium	7429-90-5	1.602	0.20	0.20	1980	1980
	encapsulation	organic material	carbon black	1333-86-4	1.109	0.14		1371
encapsulation	plastics	epoxy resin	-	79.289	9.80		97996	
	inorganic material	silicondioxide	60676-86-0	474.072	58.59	68.53	585921	685288
leadfinish	non noble metal	tin	7440-31-5	4.975	0.61	0.61	6148	6148
plating	noble metal	silver	7440-22-4	0.678	0.08	0.08	837	837
glue	plastics	epoxy resin	-	0.353	0.04		436	
	noble metal	silver	7440-22-4	1.663	0.21	0.25	2055	2491
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com